JIEJIE MICROELECTRONICS CO., LTD.

JOCMA2AC-D6P/S Series

Rev.A.1.0

DESCRIPTION:

TOe producPs Mre r6e-lpMiynsoB pTPOiecoMlQic MnAlGMAs infrMdriedoedmiinPpiuPgsPMge c coupledPoMOigO-QolPMge ouPpuPde B TOe d consisPs of MOigO-lsPMiedpiOodPeQMrr circuiPryB TOe pdreoldyuucBseMrienRMccur MuPomoPiQe NMPPery mMnMgemenPsysP NMPPer Mnd poRer sysPem insulMPion PesPi conPr EMRCreed relMy replMcemenPB

MAIN FEATURES:

- HigOisoDlOMPi0oVnrms
- Single cOMnnel ndremMPlollyeo-nS Singl
- OperMPing PemrpMenrgMPu-r40ÁFPo 110ÁF
- REAFH & RoHS compliMnce
- HBM: H3A; MM: M4; FGM: F3
- FQFMpproQed
- VGEMpproQed
- UlMpproQed

ABSOLUTE MAXIMUM RATINGS (TemperMPure = 2DÁF)

Parameter		Symbol	Value	Unit
Input	Forward Current	FI	50	mA
	Peak Forward Current	IFP	1⁷	$
	5HYHUVH 9ROWDJH	95		
	3RZHU 'LVVLSDWLRQ	3'		
2XWSXW	6ZLWFKLQJ 9ROWDJH	2	9	
	&RQWLQXRXV /RDG &XUUHQW	R		
	3RZHU 'LVVLSDWLRQ	3&		P:
2SHUDWLQJ 7HPSHUDWXUH		7RSU	a	
-XQFWLRQ 7HPSHUDWXUH		7M		
6WRUDJH 7HPSHUDWXUH		7VWJ	a	
7RWDO 3RZHU 'LVVLSDWLRQ		3WRW		P:
,VRODWLRQ 9ROWDJH		9LVR	8	9UPV

Soldering Temperature	T_{sol}	260	

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ELECTRICAL CHARACTERISTICS (Temperature = 25ÁC)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F = 10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R = 6V	-	-	1	εA
	Terminal Capacitance	C_t	V = 0, f = 1MHz	-	70	-	pF
	Reset Current	$I_{F(OFF)}$	$I_O = I_{O(MAX)}$	0.1	-	-	mA
Output	Open-circuit leakage current	I_{Leak}	V_O =				

ORDERING INFORMATION

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Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

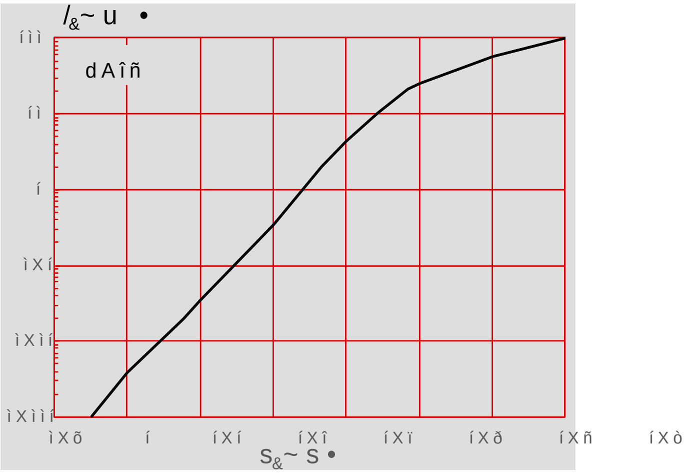


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

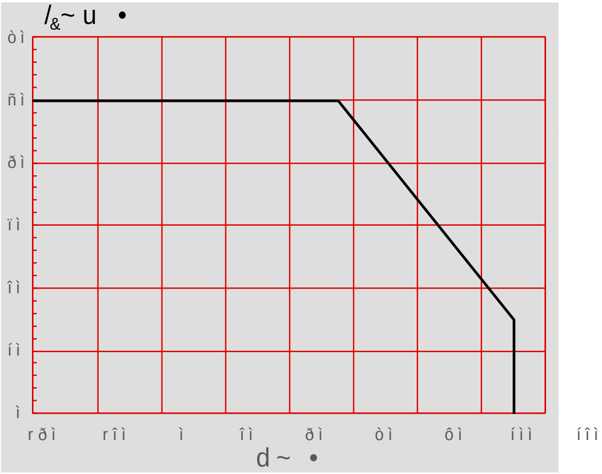


FIG.3: LED Operate Current vs. Ambient Temperature

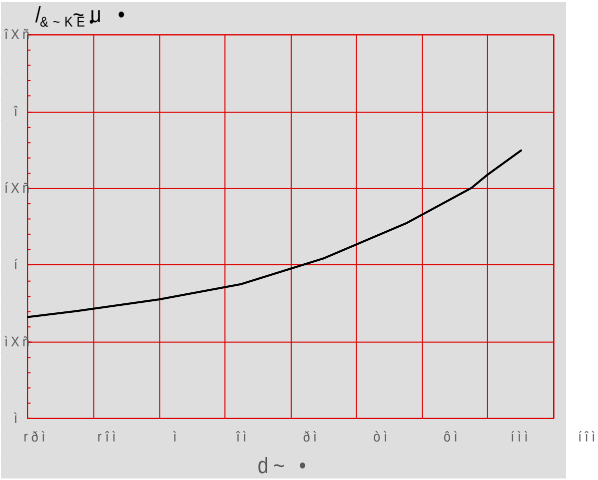


FIG.4: On Resistance vs. Ambient Temperature

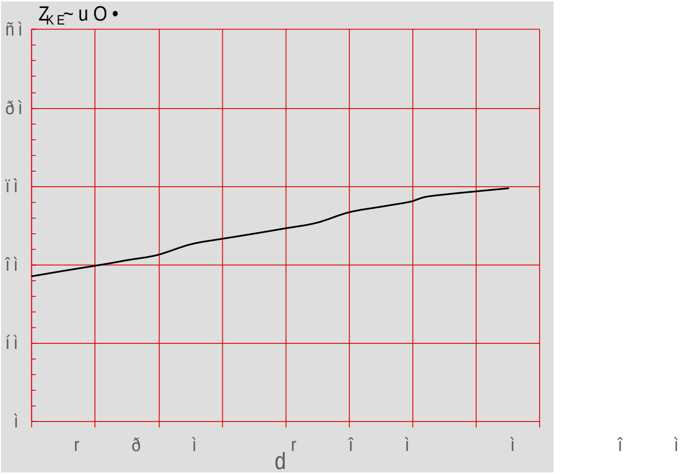


FIG.5: Turn On Time vs. Ambient Temperature

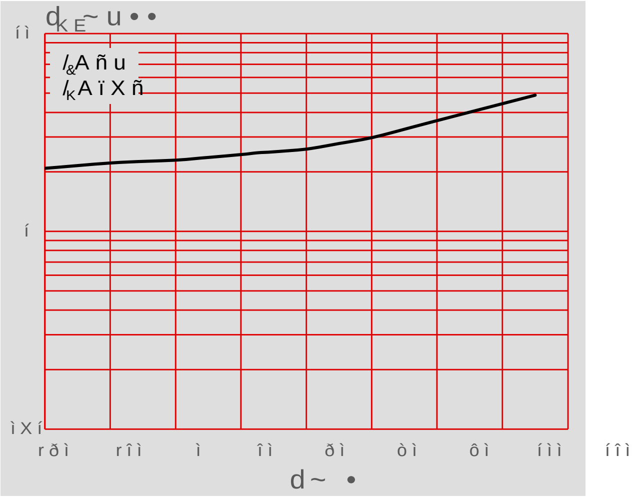
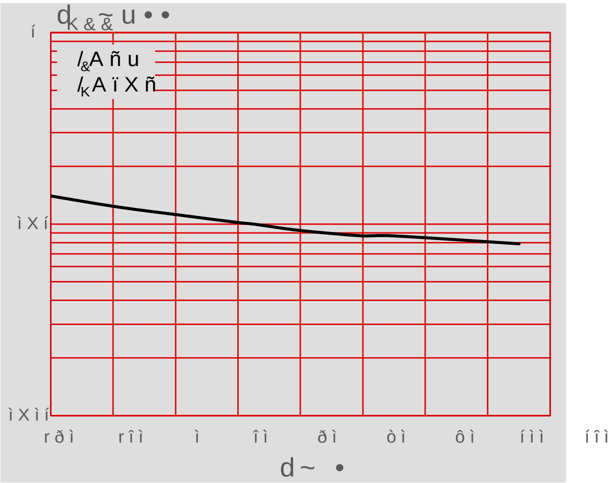
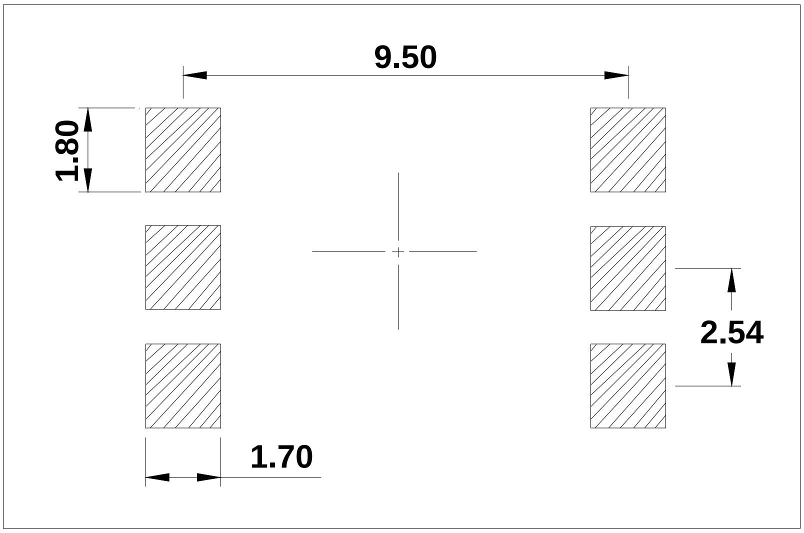


FIG.6: Turn Off Time vs. Ambient Temperature



RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option SMD



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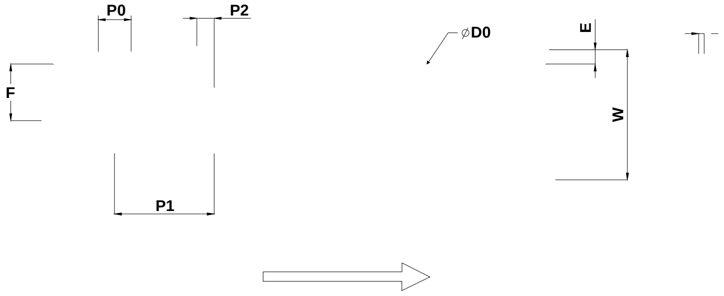
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S/L



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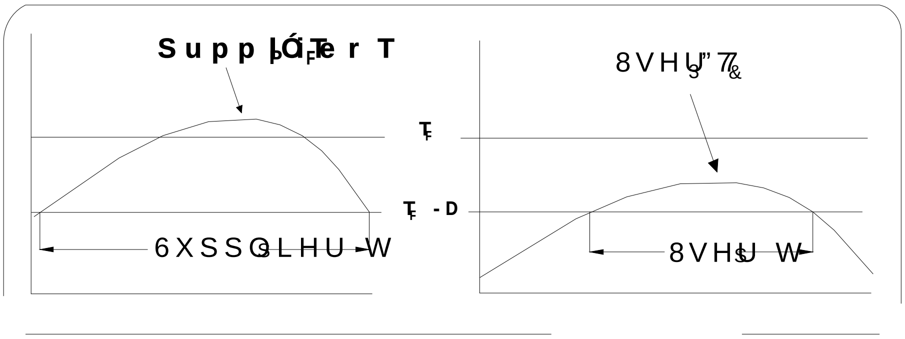
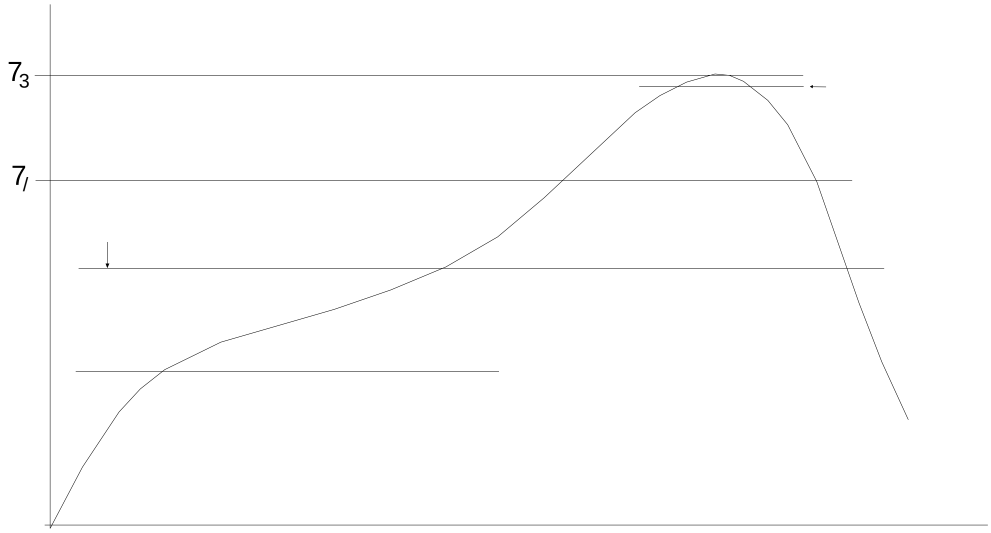
REFLOW INFORMATION





WAVE SOLDERING

HAND SOLDERING BY SOLDERING IRON

6ROGHULQJ 7HPSHUDWXUH	f
6ROGHULQJ 7LPH	V PD[

Note:

1. Reflow soldering is recommended at the temperatures and time shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf lif